

DFLU1200-p, DFLU1400-p, DFLU1600-p

Part Number: **DFLUxxxx-p**
Weight (mg): 18.1156

p = package designator
See Data Sheet

Element	Material Group	Materials	CAS (if applicable)	Average mass homogeneous Material(%)	Percent of whole (%)	Mass (mg)	ppm Homogeneous Material	ppm overall
Chip	Silicon w/Metal	Doped Silicon *	7440-21-3	100.00%	4.77	0.864	1000000	47694
Leadframe & Clip	CDA194	Cu	7440-50-8	97.40%	50.64	9.1744	974000	493269
		Fe	1309-37-1	2.40%			24000	12154
		P	7723-14-0	0.08%			800	405
		Zn	7440-66-6	0.12%			1200	608
Encapsulation	EME-G600	SiO2	60676-86-0	87.45%	38.50	6.9745	874500	336682
		Epoxy Resin	-----	5.00%			50000	19250
		Phenol Resin	-----	5.00%			50000	19250
		Cresol Novolac	29690-82-2	2.00%			20000	7700
		C	1333-86-4	0.50%			5000	1925
		Bismuth/Bismuth compound	-----	0.05%			500	192
Die Attach Solder	PbSnAg High Temp Solder	Pb	7439-92-1	95.50%	4.14	0.7491	955000	39490
		Ag	7440-22-4	2.50%			25000	1034
		Sn	7440-31-5	2.00%			20000	827
Lead Plating Finish	Matte Tin	Tin	7440-31-5	100.00%	1.95	0.3536	1000000	19519
					Total	100.00	18.12	1000000

Tolerance ±10%

This data is based on information provided by our suppliers. We believe it to be correct but do not routinely validate it by measurement. It is for guidance only and Diodes Inc. does not guarantee its absolute accuracy or completeness. Compliance to RoHS is confirmed by third party lab test results. Tests are conducted approximately annually.

* The Silicon Chip is doped at atomic levels with trace amounts of elements that may include Phosphorus, Boron, Arsenic, and other elements. Metalization may include Titanium, Nickel, Aluminum, Silver or Gold. These substances are not reported where their concentration is less than the minimum reportable level per the guidelines specified in the Tables of EIA JIG-101, Material Composition Declaration for Electronic Products.

This product or product family does not contain any of the following substances except as **CURRENTLY** exempted by ELV II and RoHS and reported above:

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| Asbestos | Organic tin compounds |
| Antimony Compounds | Ozone Depleting Substances - Class I (CFCs, HBFCs, etc.) |
| Azo compounds | Ozone Depleting Substances - Class II (HCFCs) |
| Cadmium and cadmium compounds | Perfluorooctane Sulphonate (PFOS) or related compounds |
| Certain Shortchain Chlorinated Paraffins | Polybrominated biphenyls (PBB) and Polybrominated diphenyl ethers (PBDE) including DecaBDE |
| Chlorinated organic compounds | Polychlorinated Biphenyls (PCBs) |
| Halogens | Polychlorinated Naphthalenes (> 3 chlorine atoms) |
| Hexavalent chromium compounds | Radioactive Substances |
| Lead and lead compounds | Tributyl Tin (TBT) and Triphenyl Tin (TPT) |
| Mercury and mercury compounds | Tributyl Tin Oxide (TBTO) |

REACH SVHCs: